



Material Content Data Sheet



Sales Product Name		IPD30N03S2L-10		Issued		29. August 2013		
MA#		MA000254531						
Package		PG-TO252-3-11		Weight*		370.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.654	0.72	0.72	7172	7172
leadframe	non noble metal	iron	7439-89-6	0.234	0.06		634	
	inorganic material	phosphorus	7723-14-0	0.070	0.02		190	
	non noble metal	copper	7440-50-8	234.187	63.29	63.37	632699	633523
wire	non noble metal	aluminium	7429-90-5	0.936	0.25	0.25	2528	2528
encapsulation	organic material	carbon black	1333-86-4	1.263	0.34		3413	
	plastics	epoxy resin	-	22.105	5.97		59722	
	inorganic material	silicondioxide	60676-86-0	102.948	27.81	34.12	278135	341270
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10104	10104
plating	non noble metal	nickel	7440-02-0	0.091	0.02		245	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	246
solder	noble metal	silver	7440-22-4	0.048	0.01		129	
	non noble metal	tin	7440-31-5	0.038	0.01		103	
	non noble metal	lead	7439-92-1	1.823	0.49	0.51	4925	5157
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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